



(1.27 mm) .050"

CLP-107-02-F-D-P

CLP-115-02-L-D

CLP-130-02-L-D

CLP-116-02-F-DH

CLP SERIES

LOW-PROFILE DUAL WIPE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Sn or Au over

50 μ" (1.27 μm) Ni

Current Rating (CLP/FTSH):

3.4 A per pin

(2 pins powered)

Voltage Rating:

280 VAC/395 VDC

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

Top Entry = (1.40 mm) .055"

minimum, Bottom Entry =

(2.41 mm) .095" minimum

plus board thickness

DH Entry = (2.31 mm) .091"

to (2.67 mm) .105"

Normal Force:

60 grams (0.59 N) average

Max Cycles:

100 with 10 μ" (0.25 μm) Au

RoHS Compliant:

Yes

Mates with:

FTSH, FTS, FW

APPLICATIONS

CLP FTSH

HORIZONTAL

PASS-THRU

High-reliability
Tiger Claw™
contacts

(1.27 mm x 1.27 mm)
.050" x .050"
micro pitch

Low-profile
(2.21 mm)
.087"

Surface
mount

Suitable for pass-through
applications



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-35)

(0.15 mm) .006" max (36-50)*

*(.004" stencil solution

may be available; contact

IPG@samtec.com)

RECOGNITIONS

For complete scope of

recognitions see

www.samtec.com/quality



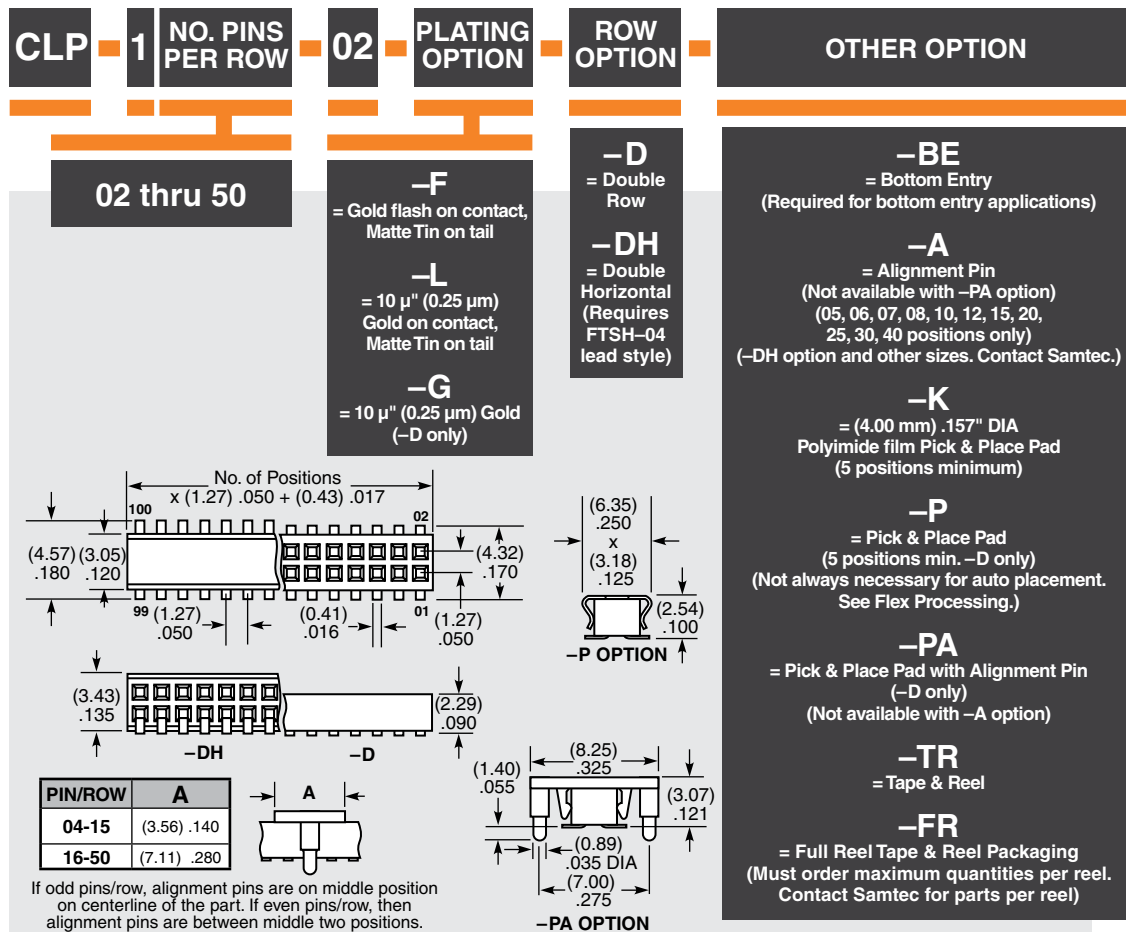
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ALSO AVAILABLE (MOQ Required)

- Single row
- Other platings

Note:

Some sizes, styles and options are non-standard, non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.